

*Amendment*

In response to the Office Action dated May 31, 2002, please amend the application as follows:

IN THE CLAIMS:

Please amend Claims 1 and 9 and add Claim 21 as follows. A marked-up copy of Claims 1 and 9 showing the changes made thereto, is attached. Note that all the claims currently pending in this application, including those not presently amended, have been reproduced below for the Examiner's convenience.

1. (Twice Amended) A mini-environment pod device, said device being free to be installed in and uninstalled from a shielded chamber for containing a micro-device manufacturing apparatus for a micro-device manufacturing apparatus, comprising:

B/ a cassette being able to hold a substrate, the substrate being transported to the apparatus and processed;

a pod providing an inner space to store said cassette, said pod including an outer surface where an electromagnetic shield is disposed and an opening; and

a lid which fits into the opening of said pod, said lid providing an isolated environment in the inner space,

wherein when said pod is installed in the shielded chamber, the electromagnetic shield of said pod becomes in a conductive relationship with the shielded chamber, and

when said pod is installed in the shielded chamber, said lid is removed from the opening of said pod along a portion of the shielded chamber, and the substrate in said

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cassette is transported to the apparatus, the electromagnetic shield of said pod inhibits  
leakage of electromagnetic waves from the inside of the shielded chamber through the  
opening of said pod to the outside of said pod.

2. (Unamended) A device according to Claim 1, wherein said mini-environment pod  
is a front opening type having the opening in the front of the pod.

3. (Unamended) A device according to Claim 1, wherein said mini-environment pod  
is a bottom opening type having the opening in the bottom of the pod.

5. (Unamended) A device according to Claim 1, wherein said electromagnetic shield  
comprises wire mesh provided on or within walls of said pod.

6. (Unamended) A device according to Claim 1, wherein said electromagnetic shield  
comprises metal coatings provided on walls of said pod.

7. (Unamended) A device according to Claim 1, wherein said electromagnetic shield  
comprises shielding materials provided in walls of said pod.

8. (Unamended) A device according to Claim 1, wherein said electromagnetic shield  
has a shielding capacity of under 100 dB ( $\mu$ V) within frequencies of about 9 kHz to about  
400 MHz.

9. (Twice Amended) A micro-device manufacturing apparatus for processing a substrate, said apparatus comprising:

a shielded chamber having an opening covered with a door;

a door opener which opens the door of said shielded chamber; and

a processing system, contained in said shielded chamber, which processes the substrate in said shielded chamber; and

a pod stand for mounting a mini-environment pod device, the pod device being free to be installed in and uninstalled from said shielded chamber and comprising:

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a cassette being able to hold the substrate, the substrate being transported to said processing system and processed;

a pod providing an inner space to store the cassette, the pod including an outer surface where an electromagnetic shield is disposed and an open end; and

a lid which fits into the open end of the pod, the lid providing an isolated environment in the inner space,

wherein when the pod is installed in said shielded chamber, the electromagnetic shield of the pod becomes in a conductive relationship with said shielded chamber, and when the pod is installed in said shielded chamber, the lid is removed from the open end of the pod along with the door of said shielded chamber by said door opener and the substrate in the cassette is transported to said processing system, the electromagnetic shield of the pod inhibits leakage of electromagnetic waves from the inside of said shielded chamber through the open end of the pod to the outside of the pod.

10. (Unamended) An apparatus according to Claim 9, wherein said chamber has a grounded conductive portion around the opening, which contacts said pod when said pod is installed on said chamber.

11. (Unamended) An apparatus according to Claim 9, further comprising an optical system in said chamber for exposing the wafer with radiation.

12. (Unamended) An apparatus according to Claim 9, further comprising kinematic couplings which mount the mini-environment pod on said manufacturing apparatus.

13. (Unamended) An apparatus according to Claim 9, wherein said mini-environment pod is a front opening type having the opening in the front of the pod.

14. (Unamended) An apparatus according to Claim 9, wherein said min-environment pod is a bottom opening type having the opening in the bottom of the pod.

15. (Unamended) An apparatus according to Claim 9, wherein said electromagnetic shield comprises wire mesh provided on or within walls of said pod.

16. (Unamended) An apparatus according to Claim 9, wherein said electromagnetic shield comprises metal coatings provided on walls of said pod.

17. (Unamended) An apparatus according to Claim 9, wherein said electromagnetic shield comprises shielding materials provided in walls of said pod.

18. (Unamended) An apparatus according to Claim 9, wherein said electromagnetic shield has a shielding capacity of under 100 dB ( $\mu$ V) within frequencies of about 9 kHz to about 400 MHz.

19. (Unamended) A semiconductor manufacturing method, comprising:

providing a min-environment pod device, which comprises (i) a cassette being able to hold a plurality of wafers, (ii) a pod providing an inner space to store the cassette, wherein the pod has an electromagnetic shield, and (iii) a lid which fits into an opening of the pod, the lid providing an isolated environment in the inner space;

providing a micro-device manufacturing apparatus, which comprises (i) a shielded chamber having an opening covered with a door, (ii) a door opener which opens the door of the chamber and the lid of the pod when the pod is installed on the apparatus and (iii) a processing system which processes the wafer in the chamber, wherein the electromagnetic shield of the pod is in a conductive relationship with the chamber when the pod is installed on the chamber;

installing the mini-environment pod onto the manufacturing apparatus;

opening both the door of the chamber and the lid of the pod to expose the wafer to the inside atmosphere of the chamber;